198 Champion Court San Jose, CA 95134-1709 (408) 943-2600

PRODUCT INFORMATION NOTIFICATION

PIN: PIN135261 **Date:** December 13, 2013

Subject: Qualification of Polyimide Process for 1Mb, 2Mb, 4Mb, 8Mb, 16Mb, 32Mb, and 64Mb MoBL® Asynchronous SRAM Devices

To: PCN ADMIN
CYPRESS
pcn_adm@cypress.com

Change Type: Minor

Description of Change:
Cypress is adding a polyimide stress-relief layer to the 90nm process technology based 1Mb, 2Mb, 4Mb, 8Mb, 16Mb, 32Mb, and 64Mb MoBL® (low-power) Asynchronous SRAM devices. The devices are fabricated at Cypress Minnesota. The polyimide layer is applied on top of the existing nitride passivation layer for stress relief. A polyimide layer on top of passivation is widely used by the semiconductor industry as a best practice for stress relief. There are no changes to the existing circuits or processing of the device die itself.

The polyimide process is being introduced as part of Cypress' continuous quality improvement program for the 90nm process technology node.

There are no changes to the existing datasheets, which can be downloaded from the Cypress website (www.cypress.com).

Benefit of Change:
The polyimide layer protects the die from package stresses thereby improving its reliability.

Affected Part Numbers: 352
Affected Parts: Please see attachment for list of parts

Customer Part Numbers Affected:
Affected Parts: Not Applicable

Qualification Status:
This polyimide process has been qualified through a series of tests identified with the results added to the existing product Qual Reports. See the table below.

The product qualification (QTP) reports can be found in the attachment to this notification or by

visiting www.cypress.com, typing the QTP number in the search window, and clicking on the magnifying glass icon.

Approximate Implementation Date:
Effective 90 days from the date of this notification, Cypress will start transition to shipments of the affected part numbers with polyimide material.

Anticipated Impact:
Products manufactured are completely compatible with existing product from a functional, parametric, and quality performance perspective.
Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:
Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:
This is an information only announcement. No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration